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Inventor Name Search Result

Your Search was:

Last Name = LEEDY
First Name = GLEN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 51
60402112	Not Issued	159	08/08/2002	VERTICAL SYSTEM INTEGRATION	LEEDY, GLENN J.
10865579	Not Issued	030	06/09/2004	SYSTEM FOR PROBING, TESTING, BURN-IN, REPAIRING AND PROGRAMMING OF INTEGRATED CIRCUITS	LEEDY, GLENN
10766629	Not Issued	041	01/27/2004	APPARATUS AND METHODS FOR MASKLESS PATTERN GENERATION	LEEDY, GLENN JOSEPH
10766557	Not Issued	019	01/27/2004	METHODS FOR MASKLESS LITHOGRAPHY	LEEDY, GLENN JOSEPH
10742387	Not Issued	030	12/18/2003	METHOD OF INFORMATION PROCESSING USING THREE DIMENSIONAL INTEGRATED CIRCUITS	LEEDY, GLENN J.
10742282	Not Issued	030	12/19/2003	MEMBRANE 3D IC FABRICATION	LEEDY, GLENN JOSEPH
10742057	Not Issued	030	12/18/2003	MEMBRANE 3D IC FABRICATION	LEEDY, GLENN JOSEPH
10741647	Not Issued	019	12/18/2003	MEMBRANE 3D IC FABRICATION	LEEDY, GLENN JOSEPH
10741602	Not Issued	020	12/18/2003	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY, GLENN J.
10724031	Not Issued	019	11/26/2003	LITHOGRAPHY DEVICE FOR SEMICONDUCTOR CIRCUIT PATTERN GENERATION	LEEDY, GLENN JOSEPH
10700429	Not Issued	030	11/03/2003	MEMBRANE IC FABRICATION	LEEDY, GLENN JOSEPH

10672961	Not Issued	030	09/26/2003	THREE DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT	LEEDY, GLENN J.
10665757	Not Issued	030	09/19/2003	METHODOF MAKING AN INTEGRATED CIRCUIT	LEEDY, GLENN J.
10614067	Not Issued	030	07/03/2003	THREE DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT	LEEDY, GLEN J.
10485046	Not Issued	020	01/22/2004	VERTICAL SYSTEM INTEGRATION	LEEDY, GLENN J.
10460483	Not Issued	030	06/11/2003	STRESS-CONTROLLED DIELECTRIC INTEGRATED CIRCUIT	LEEDY, GLENN JOSEPH
10460027	Not Issued	092	06/11/2003	STREES-CONTROLLED DIELECTRIC INTEGRATED CIRCUIT	LEEDY, GLENN J.
10385386	Not Issued	041	03/07/2003	LITHOGRAPHY DEVICE FOR SEMICONDUCTOR CIRCUIT PATTERN GENERATOR	LEEDY, GLENN JOSEPH
10379820	Not Issued	041	03/03/2003	THREE DIMENSIONAL INTEGRATED CIRCUIT STRUCTURE HAVING A BONDING LAYER	LEEDY, GLENN J.
10355558	Not Issued	041	01/31/2003	METHOD AND APPARATUS FOR PROBING, TESTING, BURN-IN, REPAIRING AND PROGRAMMING OF INTEGRATED CIRCUITS IN A CLOSED ENVIRONMENT USING A SINGLE APPARATUS	LEEDY, GLENN J.
10222816	Not Issued	030	08/19/2002	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY, GLENN J.
10144791	6563224	150	05/15/2002	THREE DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT	LEEDY, GLENN J.
10143200	Not Issued	041	05/13/2002	RECONFIGURABLE INTEGRATED CIRCUIT MEMORY	LEEDY, GLENN J.
09946552	Not Issued	094	09/06/2001	METHOD AND SYSTEM FOR PROBING, TESTING, BURN-IN, REPAIRING AND PROGRAMMING OF INTEGRATED CIRCUITS IN A CLOSED ENVIRONMENT USING A SINGLE APPARATUS	LEEDY, GLENN
09776885	6551857	150	02/06/2001	THREE DIMENSIONAL STRUCTURE INTEGRATED	LEEDY, GLENN J.

				CIRCUITS	
09775670	6713327	150	02/05/2001	STRESS CONTROLLED DIELECTRIC INTEGRATED CIRCUIT FABRICATION	LEEDY, GLENN JOSEPH
09775598	6765279	150	02/05/2001	MEMBRANE 3D IC FABRICATION	LEEDY, GLENN JOSEPH
09775597	6682981	150	02/05/2001	STRESS CONTROLLED DIELECTRIC INTEGRATED CIRCUIT FABRICATION	LEEDY, GLENN JOSEPH
09607363	6632706	150	06/30/2000	THREE DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT FABRICATION PROCESS	LEEDY, GLENN J
08813439	5840593	150	03/10/1997	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY, GLENN JOSEPH
08488380	6294909	150	06/07/1995	ELECTRO-MAGNETIC LITHOGRAPHIC ALIGNMENT METHOD	LEEDY, GLENN J
08486526	5629137	150	06/07/1995	METHOD OF REPAIRING AN INTEGRATED CIRCUIT STRUCTURE	LEEDY, GLENN J.
08486525	Not Issued	161	06/07/1995	TESTER HEAD ASSEMBLY FOR TESTING AN INTEGRATED CIRCUIT USING HIGH DENSITY PROBE POINTS	LEEDY, GLENN J.
08486521	5725995	150	06/07/1995	METHOD OF REPAIRING DEFECTIVE TRACES IN AN INTEGRATED CIRCUIT STRUCTURE	LEEDY, GLENN J.
08484144	5834334	150	06/07/1995	METHOD OF FORMING A MULTI-CHIP MODULE FROM A MEMBRANE CIRCUIT	LEEDY, GLENN J
08484029	5592007	150	06/07/1995	MEMBRANE DIELECTRIC ISOLATION TRANSISTOR FABRICATION	LEEDY, GLENN J.
08483731	6714625	150	06/07/1995	LITHOGRAPHY DEVICE FOR SEMICONDUCTOR CIRCUIT PATTERN GENERATION	LEEDY, GLENN J
08483248	5654127	150	06/07/1995	METHOD OF MAKING A TESTER SURFACE WITH HIGH DENSITY PROBE POINTS	LEEDY, GLENN J.
08478476	5580687	150	06/07/1995	A CONTACT STEPPER PRINTED LITHOGRAPHY METHOD	LEEDY, GLENN J.

08477785	5637907	150	06/07/1995	THREE DIMENSIONAL SEMICONDUCTOR CIRCUIT STRUCTURE WITH OPTICAL INTERCONNECTION	LEEDY , GLENN J.
08475796	5592018	150	06/07/1995	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
08475770	5654220	150	06/07/1995	METHOD OF MAKING A STACKED 3D INTEGRATED CIRCUIT STRUCTURE	LEEDY , GLENN J.
08474489	6288561	150	06/07/1995	METHOD AND APPARATUS FOR PROBING, TESTING, BURN-IN, REPAIRING AND PROGRAMMING OF INTEGRATED CIRCUITS IN A CLOSED ENVIRONMENT USING A SINGLE APPARATUS	LEEDY , GLENN
08474449	5571741	150	06/07/1995	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
08474448	5633209	150	06/07/1995	METHOD OF FORMING A CIRCUIT MEMBRANE WITH A POLYSILICON FILM	LEEDY , GLENN J.
08472426	5946559	150	06/07/1995	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
08315905	5869354	150	09/30/1994	METHOD OF MAKING DIELECTRICALLY ISOLATED INTEGRATED CIRCUIT	LEEDY , GLENN J.
08217410	5453404	150	03/24/1994	METHOD FOR MAKING AN INTERCONNECTION STRUCTURE FOR INTEGRATED CIRCUITS	LEEDY , GLENN
08146470	5512397	150	11/02/1993	STEPPER SCANNER DISCRETIONARY LITHOGRAPHY AND COMMON MASK DISCRETIONARY LITHOGRAPHY FOR INTEGRATED CIRCUITS	LEEDY , GLENN J.
08055439	5451489	150	04/30/1993	MAKING AND TESTING AN INTEGRATED CIRCUIT USING HIGH DENSITY PROBE POINTS	LEEDY , GLENN J.
07194596	4924589	150	05/16/1988	METHOD OF MAKING AND TESTING AN INTEGRATED CIRCUIT	LEEDY , GLENN J.

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Application#	Patent#	Status	Date Filed	Title	Inventor Name 18
09028081	6008126	150	02/23/1998	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN JOSEPH
09027959	Not Issued	161	02/23/1998	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN JOSEPH
08971565	6133640	150	11/17/1997	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY , GLENN J.
08971367	6208545	150	11/17/1997	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY , GLENN J.
08850749	5985693	150	05/02/1997	HIGH DENSITY THREE-DIMENSIONAL IC INTERCONNECTION	LEEDY , GLENN JOSEPH
08835190	5915167	150	04/04/1997	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY , GLENN J
08813439	5840593	150	03/10/1997	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN JOSEPH
08779679	6020257	150	01/07/1997	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
08701736	Not Issued	168	08/22/1996	MAKING AND TESTING AN INTEGRATED CIRCUIT	LEEDY , GLENN J.
07960588	5323035	150	10/13/1992	INTERCONNECTION STRUCTURE FOR INTEGRATED CIRCUITS AND METHOD FOR MAKING SAME	LEEDY , GLENN
07865412	5354695	150	04/08/1992	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
07838157	Not Issued	166	02/18/1992	STEPPER SCANNER DISCRETIONARY LITHOGRAPHY AND COMMON MASK DISCRETIONARY LITHOGRAPHY FOR	LEEDY , GLENN J.

				INTEGRATED CIRCUITS	
07775324	5225771	150	10/11/1991	MAKING AND TESTING AN INTEGRATED CIRCUIT USING HIGH DENSITY PROBE POINTS	LEEDY , GLENN J.
07482135	5103557	150	02/16/1990	MAKING AND TESTING AN INTEGRATED CIRCUIT USING HIGH DENSITY PROBE POINTS	LEEDY , GLENN J.
07436396	5034685	250	11/14/1989	TEST DEVICE FOR TESTING INTEGRATED CIRCUITS	LEEDY , GLENN J.
07436395	5020219	150	11/14/1989	METHOD OF MAKING A FLEXIBLE TESTER SURFACE FOR TESTING INTEGRATED CIRCUITS	LEEDY , GLENN J.
07436278	4994735	150	11/14/1989	FLEXIBLE TESTER SURFACE FOR TESTING INTEGRATED CIRCUITS	LEEDY , GLENN J.
06661550	Not Issued	161	10/15/1984	MULTIPLE PROCESSOR COMPUTER SYSTEM	LEEDY , GLENN J.

Inventor Search Completed: No Records to Display.

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1	BRS	15	("4500905" "4939568" "4892753" "5000113" "5240458" "5259247" "6087284" "6518073").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:14
2	BRS	0	"RE 34893"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:24
3	BRS	2	jp-04196263-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:39
4	BRS	67	("2915722" "3202948" "3559282" "3560364" "3602982" "3615901" "3716429" "3777227" "3868565" "3922705" "3997381" "4070230" "4131985" "4142004" "4251909" "4262631" "4394401" "4401986" "4416054" "4539068" "4585991" "4612083" "4617160" "4618397" "4618763" "4663559" "4684436" "4693770").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:32
5	BRS	57	US-4702336-$.DID. OR US-4702936-$.DID. OR US-4706166-$.DID. OR US-4721938-$.DID. OR US-4761681-$.DID. OR US-4784721-$.DID. OR US-4810673-$.DID. OR US-4825277-$.DID. OR US-4857481-$.DID. OR US-4924589-$.DID. OR US-4940916-$.DID. OR US-4950987-$.DID. OR US-4952446-$.DID. OR US-4954865-$.DID. OR US-4957882-$.DID. OR US-4965415-$.DID. OR US-4966663-$.DID. OR US-4994735-$.DID. OR US-5008619-$.DID. OR US-5010024-$.DID. OR US-5020219-$.DID. OR US-5034685-$.DID. OR US-5070026-$.DID. OR US-5071510-$.DID. OR US-5098865-$.DID. OR US-5103557-$.DID. OR US-0510373-$.DID. OR US-0511278-$.DID. OR US-5116777-$.DID. OR US-5130894-$.DID. OR US-5132244-$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:34

	Type	Hits	Search Text	DBs	Time Stamp
6	BRS	61	US-5151775-$.DID. OR US-5156909-$.DID. OR US-5203731-$.DID. OR US-5225771-$.DID. OR US-0523618-$.DID. OR US-5262351-$.DID. OR US-5270261-$.DID. OR US-5273940-$.DID. OR US-5274270-$.DID. OR US-5279865-$.DID. OR US-5284796-$.DID. OR US-5323035-$.DID. OR US-5324687-$.DID. OR US-5354695-$.DID. OR US-5363021-$.DID. OR US-5385909-$.DID. OR US-5385632-$.DID. OR US-5420458-$.DID. OR US-5424920-$.DID. OR US-5426072-$.DID. OR US-5426363-$.DID. OR US-5432444-$.DID. OR US-5432729-$.DID. OR US-5434500-$.DID. OR US-5451489-$.DID. OR US-5453404-$.DID. OR US-5457879-$.DID. OR US-5476813-$.DID. OR US-5489554-$.DID. OR US-5502667-$.DID. OR US-5512397-$.DID. OR US-5527645-$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:36

	Type	Hits	Search Text	DBs	Time Stamp
7	BRS	50	US-5529829-$.DID. OR US-5534465-$.DID. OR US-0555512-$.DID. OR US-5563084-$.DID. OR US-5571741-$.DID. OR US-5580687-$.DID. OR US-5581498-$.DID. OR US-5582939-$.DID. OR US-5583688-$.DID. OR US-5592007-$.DID. OR US-5592018-$.DID. OR US-5595933-$.DID. OR US-5606186-$.DID. OR US-0562712-$.DID. OR US-5629137-$.DID. OR US-5633209-$.DID. OR US-5637536-$.DID. OR US-5654127-$.DID. OR US-5654220-$.DID. OR US-5656552-$.DID. OR US-5675185-$.DID. OR US-5694588-$.DID. OR US-5725995-$.DID. OR US-0575021-$.DID. OR US-5760478-$.DID. OR US-5773152-$.DID. OR US-0578616-$.DID. OR US-0579315-$.DID. OR US-5831280-$.DID. OR US-5834334-$.DID. OR US-5840593-$.DID. OR US-5856695-$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:37

	Type	Hits	Search Text	DBs	Time Stamp
8	BRS	36	US-5868949-$.DID. OR US-5869354-$.DID. OR US-5870176-$.DID. OR US-5880010-$.DID. OR US-5882532-$.DID. OR US-05902118-$.DID. OR US-5915167-$.DID. OR US-5946559-$.DID. OR US-5985693-$.DID. OR US-5998069-$.DID. OR US-6008126-$.DID. OR US-6020257-$.DID. OR US-6045625-$.DID. OR US-6084284-$.DID. OR US-6097096-$.DID. OR US-6133640-$.DID. OR US-6194245-$.DID. OR US-6197456-$.DID. OR US-6208545-$.DID. OR US-6236602-$.DID. OR US-6261728-$.DID. OR US-6288561-$.DID. OR US-6294909-$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:38
9	BRS	2	jp-60074643-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:40
10	BRS	2	jp-02082564-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:40
11	BRS	2	jp-04083371-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:40
12	BRS	2	jp-04107964-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:40
13	BRS	0	jp-40202760-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:44
14	BRS	1	gb-2215168-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:41
15	BRS	2	ep-189976-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:42

	Type	Hits	Search Text	DBs	Time Stamp
16	BRS	2	ep-731525-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:42
17	BRS	2	fr-2641129-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:43
18	BRS	1	wo-9719337-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:43
19	BRS	1	jp-02027600-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:03
20	BRS	575	438/455.ccls. and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:03
21	BRS	530	438/459.ccls. and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:04
22	BRS	432	438/977.ccls. and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:04
23	BRS	544	438/109.ccls. and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:04
24	BRS	60	(438/455.ccls. and 257/$.ccls.) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:23
25	BRS	216	(438/455.ccls. and 257/$.ccls.) and substrates with (bond bonding bonded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:23
26	BRS	39	((438/455.ccls. and 257/$.ccls.) and substrates with (bond bonding bonded)) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:24
27	BRS	2	((438/455.ccls. and 257/$.ccls.) and substrates with (bond bonding bonded)) and plurality with substrates and flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:24
28	BRS	213	substrates with (bond bonding bonded) and plurality with substrates and flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:44

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29	BRS	9	substrates with (bond bonding bonded) and plurality with substrates and flexible adj substrate and conductive adj paths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:20
30	BRS	2	substrates with (bond bonding bonded) and plurality with substrates and flexible adj substrate and thermal adj (diffusion diffuse diffused diffusing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:20
31	BRS	2	6632706.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:10
32	BRS	4	("5324687" "5563084").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:14
33	BRS	32	substrates with (bond bonding bonded) and plurality with substrates and thermal adj (diffusion diffuse diffused diffusing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:21
34	BRS	88	substrates with (bond bonding bonded) and plurality with substrates and conductive adj paths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:21
35	BRS	0	(substrates with (bond bonding bonded) and plurality with substrates and thermal adj (diffusion diffuse diffused diffusing)) and conductive adj paths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:20
36	BRS	0	substrates with (bond bonding bonded) and plurality with substrates same thermal adj (diffusion diffuse diffused diffusing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:21
37	BRS	8	substrates with (bond bonding bonded) and plurality with substrates same conductive adj paths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:21
38	BRS	33	(438/459.ccls. and 257/$.ccls.) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:23
39	BRS	164	(438/459.ccls. and 257/$.ccls.) and substrates with (bond bonding bonded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:23

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40	BRS	33	((438/459.ccls. and 257/$.ccls.) and plurality with substrates) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:24
41	BRS	2	(((438/459.ccls. and 257/$.ccls.) and substrates with (bond bonding bonded)) and plurality with substrates) and flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:24
42	BRS	2	(((438/459.ccls. and 257/$.ccls.) and plurality with substrates) and plurality with substrates) and flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:25
43	BRS	23	((438/459.ccls. and 257/$.ccls.) and substrates with (bond bonding bonded)) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:25
44	BRS	67	substrates with (bond bonding bonded) and plurality with substrates and flexible adj substrate and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:46
45	BRS	1598	257/686.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:52
46	BRS	138	257/74.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:52
47	BRS	1980	257/723.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:52
48	BRS	1543	257/724.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:52